



Koh Young at SEMICON West with a Focus on Inspection & Metrology for Semiconductor and Advanced Packaging Challenges

Atlanta, GA – Koh Young, the industry leader in True3D™ measurement-based inspection solutions, will demonstrate its ZenStar and Meister Series of automated inspection and metrology tools for semiconductor and advanced package applications in booth 1833 at SEMICON West, taking place from July 9-11, 2024, at the Moscone Center in San Francisco, CA.

For over two decades, Koh Young has been a global leader in the field of 3D inspection and measurement technology. Our journey began with a vision to enhance precision and efficiency in electronics manufacturing. Today, we stand at the forefront of revolutionizing the semiconductor industry with our innovative metrology solutions. Using our True3D™ measurement-based inspection technologies, including the ZenStar and Meister Series, manufacturers can tackle critical manufacturing challenges in advanced packaging. These technologies provide real-time insights and predictive analytics to drive smarter manufacturing decisions, achieve higher yields, reduce defects, and improve overall productivity.

Meister S Premium In-line 3D Inspection System for Micro Solder Paste Deposits

Combining innovative vision algorithms and high-resolution optic technology, the Meister S is the ultimate, True 3D SPI solution for the semiconductor & Mini/Micro-LED packaging process improvement.

- High-resolution optics with a high-speed camera system (0.1 μm Z resolution)
- High-speed 25 Mega-pixel Camera with 3.5-micron Resolution Optics
- 10-micron Thins Solder Paste Inspection
- Colored and Transparent Flux Inspection



Meister D+ Breakthrough in 3D Measurement for Highly Reflective, Shiny Die

The Meister D+ combines industry-leading Moiré technology to inspect for micro cracks, chipping, foreign material, and more and our new proprietary optics to support highly-reflective die inspection, a challenge historically plaguing the industry.

- Small Die and Component Inspection (0201 metric / 008004 EIA)
- Narrow-gap Inspection down to 50-microns
- Height and Tilt Measurement in High Density, Highly Reflective Applications



ZenStar True 3D Measurement for Wafer-level Packaging Applications

Combining innovative vision algorithms and high-resolution optical technology, the ZenStar inspects highly reflective die as well as components. With proprietary deep learning technology, it offers enhanced capabilities to inspect defects like micro-cracks, foreign material, chipping, and more.

- Industry-leading metrology capabilities with deep learning technology
- 10-micron diameter wafer bump inspection
- Full 3D height and tilt measurement for even highly reflective die surfaces



If you cannot attend, you can still learn more about our best-in-class inspection solutions at kohyoungamerica.com.



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About Koh Young Technology, Inc.

Established in 2002, Koh Young revolutionized the inspection market by launching the industry's first 3D Solder Paste Inspection (SPI) system using a patented dual-projection Moiré technology. Since then, it has become the global leader in 3D measurement-based SPI and Automated Optical Inspection (AOI) equipment for the electronics industry. Based on its True3D™ measurement-based inspection technology, Koh Young has developed innovative inspection solutions for challenges with machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packages. Through its constant innovation, Koh Young has secured over 3,600 global customers, and commands the dominant global market share position in the SPI and AOI markets with over 23,000 machine installations. A customer-centric R&D focus uses our core competencies to develop innovative solutions for new and existing markets by listening to users and researching trends and applications. From the headquarters in Korea, activities spread across the world through its global sales and support infrastructure spanning Europe, Asia, and the Americas. These regional offices ensure Koh Young stays close to the market, and more importantly, its growing user base. Learn why so many electronics manufacturers trust Koh Young for reliable inspection for a smart factory at our regional website www.kohyoungamerica.com.

For More Information

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ZENSTAR & MEISTER

KOH YOUNG TECHNOLOGY

SEMICON[®] WEST
Booth 1833

True3D Inspection Solutions for Advanced and Wafer-Level Packaging